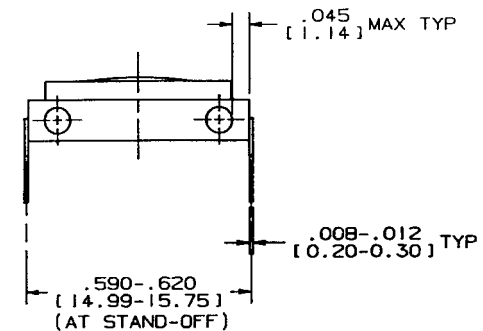
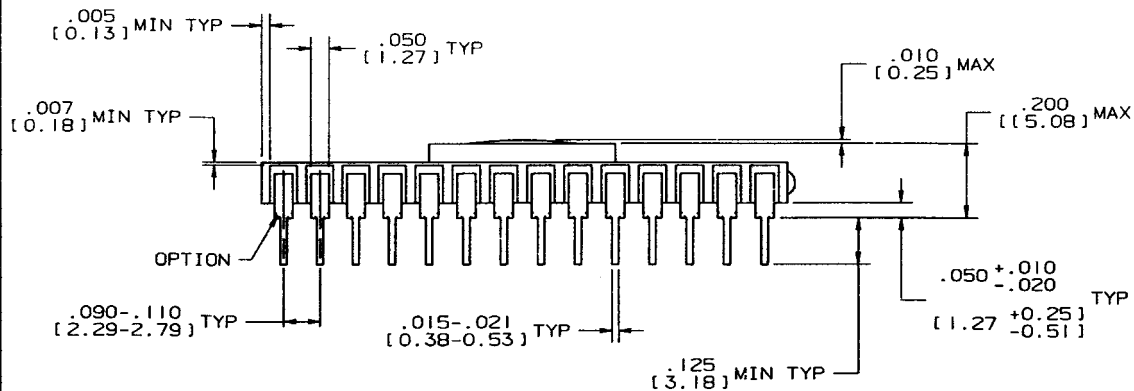
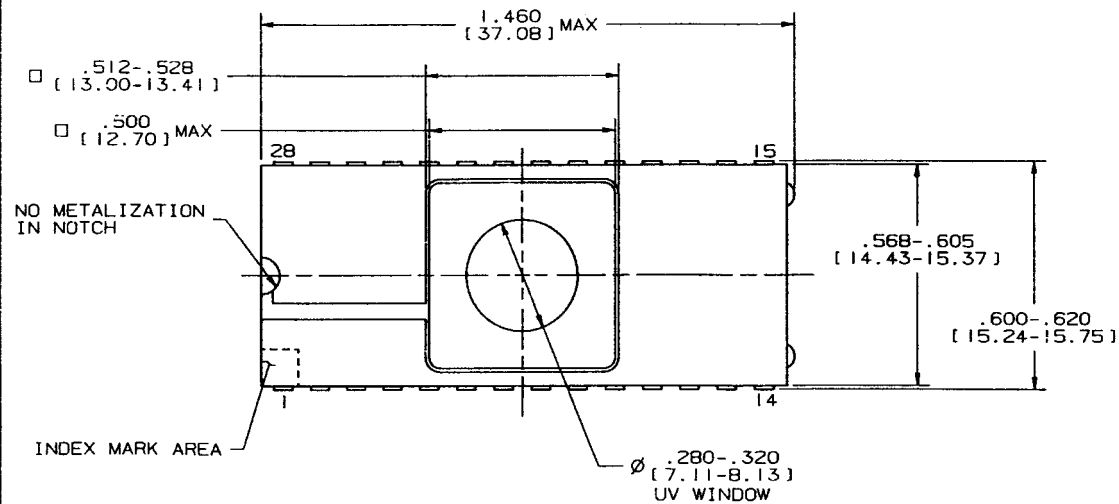


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	08264	11/14/90	PG. 52



NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:
  - a) 200 MICROINCHES/5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
  - b) 200 TO 800 MICROINCHES/5.08 TO 20.32 MICROMETERS TIN PLATE OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE OR BASIS METAL.
  - c) 50 TO 100 MICROINCHES/1.27 TO 2.54 MICROMETERS GOLD OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.
2. LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.

CONTROLLING DIMENSION: INCH				
DATE	11/14/90	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN	PAMELA GIFFORD	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DTS. CHK.	11/28/90	HERMETIC DIP(D),		
ENGR. CHK.	1/29/90	28 LEAD, EPROM,		
APPROVAL		.600 CTRS		
PROJECTION		SCALE	SIZE	DRAWING NUMBER
		N/A	C	MKT-D28JQ
		FORMERLY:	N/A	SHEET 1 OF 1
				REV A